

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Pascal C. H. Meier</td><td>08/05/2005</td></tr><tr><td>Muraleedhara Navada</td><td>08/03/2005</td></tr><tr><td>Sanjay Dabral</td><td>08/05/2005</td></tr></tbody></table>		Name	Execution Date	Pascal C. H. Meier	08/05/2005	Muraleedhara Navada	08/03/2005	Sanjay Dabral	08/05/2005		
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RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>Intel Corporation</td></tr><tr><td>Street Address:</td><td>2200 Mission College Blvd.</td></tr><tr><td>City:</td><td>Santa Clara</td></tr><tr><td>State/Country:</td><td>CALIFORNIA</td></tr><tr><td>Postal Code:</td><td>95052</td></tr></table>		Name:	Intel Corporation	Street Address:	2200 Mission College Blvd.	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052
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PROPERTY NUMBERS Total: 1											
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Application Number:	11170980										
CORRESPONDENCE DATA											
Fax Number: (203)972-7627 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone: (203) 972-0006											
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NAME OF SUBMITTER:	Randolph P. Calhoun										
Total Attachments: 3 source=P20972 - Signed Assignment#page1.tif source=P20972 - Signed Assignment#page2.tif source=P20972 - Signed Assignment#page3.tif											

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PATENT  
REEL: 016534 FRAME: 0790

Attorney Docket No.: P20972  
(BMT Ref. No.: 106.386)

## ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION

This is an Assignment of the following rights, title and interest: *(check all that apply)*

☒ United States of America rights, title and interest in the invention

☒ Foreign rights, title and interest in the invention

☒ United States Patent Application Serial No.: 11/170,980

Date of Execution:

Date of Filing: June 30, 2005

☐ United States Provisional Patent Application No.:

☐ United States Patent No(s).:

☐ International (PCT) Patent Application Serial No.:

☐ Other *(specify)*::

### TITLE OF THE INVENTION:

**A HIGH SPEED ACTIVE FLEX CABLE LINK**

### Inventors *(assignors)*

Name

Address

**Pascal C. H. Meier** 468 Southwood Avenue, Sunnyvale, CA 94068

**Muraleedhara Navada** 3707 Poinciana Drive #62, Santa Clara, CA 95051

**Sanjay Dabral** 4125 Sutherland Drive, Palo Alto, CA US 94303

### Assignee

Name

Address

**Intel Corporation** 2200 Mission College Blvd., Santa Clara, CA 95052 US

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

Attorney Docket No.: P20972  
(JMT Ref. No.: 106.386)

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to **Intel Corporation**, 2200 Mission College Blvd., Santa Clara, CA 95052 US;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for our aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures

8/5/2005  
Date

Pascal Meier  
Pascal C. H. Meier

\_\_\_\_\_  
Date

\_\_\_\_\_  
Muraleedhara Navada

8/5/2005  
Date

Sanjay Dabral  
Sanjay Dabral

Attorney Docket No.: P20972  
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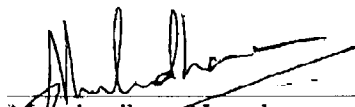
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Date

08/03/05

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Date

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Pascal C. H. Meier

  
\_\_\_\_\_  
Muraleedhara Navada

\_\_\_\_\_  
Date

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Sanjay Dabral